

Title (en)
CU-CO-SI-BASED ALLOY SHEET, AND PROCESS FOR PRODUCTION THEREOF

Title (de)
LEGIERUNGSFOLIE AUF CU-CO-SI-BASIS SOWIE HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
TÔLE EN UN ALLIAGE À BASE DE CU-CO-SI ET SON PROCÉDÉ DE PRODUCTION

Publication
EP 2578708 A4 20140409 (EN)

Application
EP 11789514 A 20110324

Priority
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• JP 2011057216 W 20110324

Abstract (en)
[origin: EP2578708A1] The present invention provides a Cu-Co-Si system alloy sheet, being suitable for use in a variety of electronic device components, in particular, having excellent uniform adhesive property for plate. The copper alloy sheet for electronic materials, contains 0.5 to 3.0 mass% Co, 0.1 to 1.0 mass% Si, the balance being Cu and unavoidable impurities, wherein an average grain size in the center part of the sheet thickness is 20 μm or less, and the number of the crystal grain, being tangent to a surface of the sheet and having 45 μm or more of the length of major axis, is 5 or less in the area of 1 mm in a rolling direction.

IPC 8 full level
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Citation (search report)
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• [X] WO 2010013790 A1 20100204 - FURUKAWA ELECTRIC CO LTD [JP], et al & US 2011186192 A1 20110804 - MIHARA KUNITERU [JP], et al
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• See references of WO 2011152104A1

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